
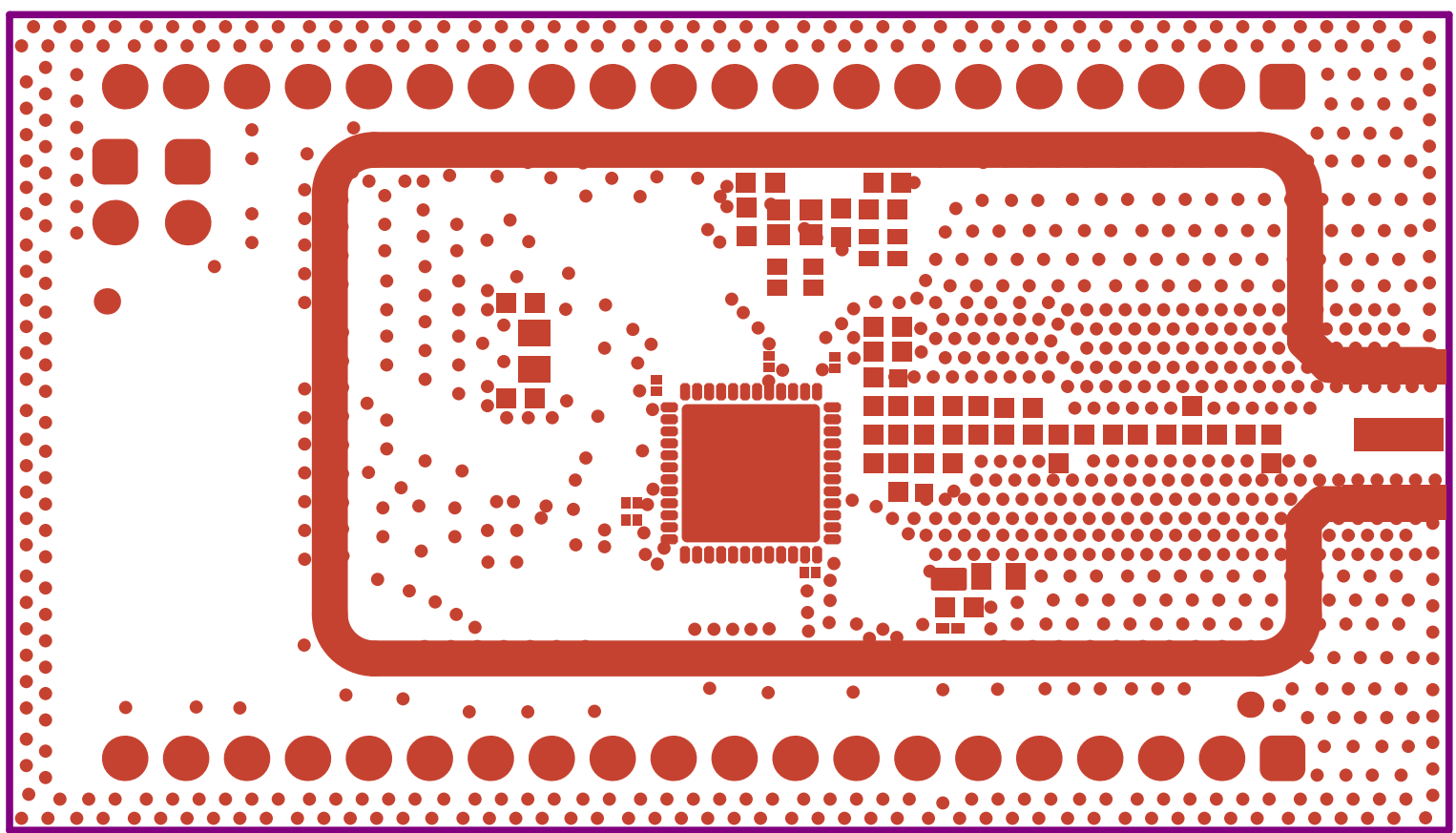

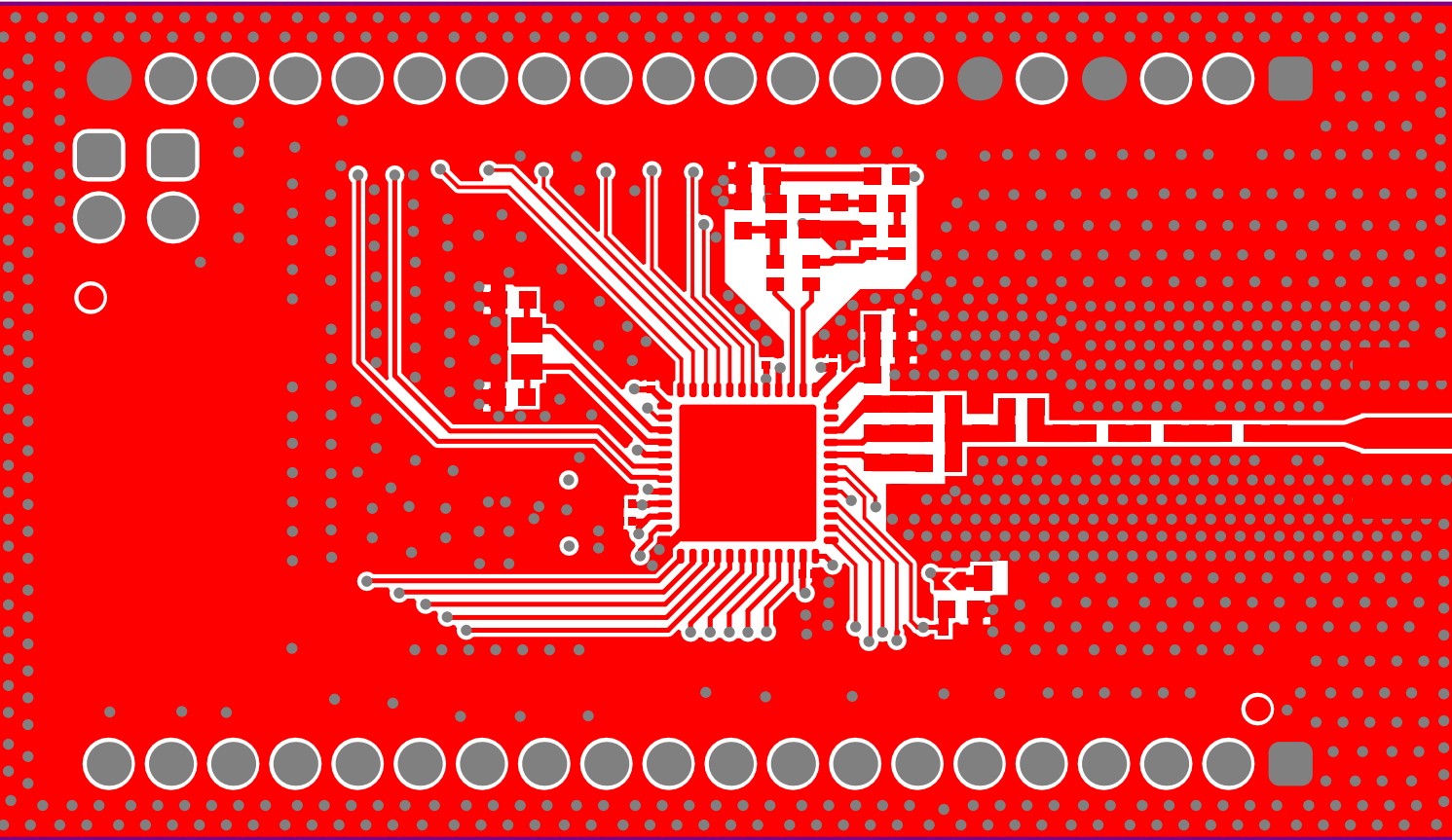



Project: STM32WL_QFN48_LP_DirectTie_RefBoard		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1789_LP	
Date: 01-04-2022	Rev: A	

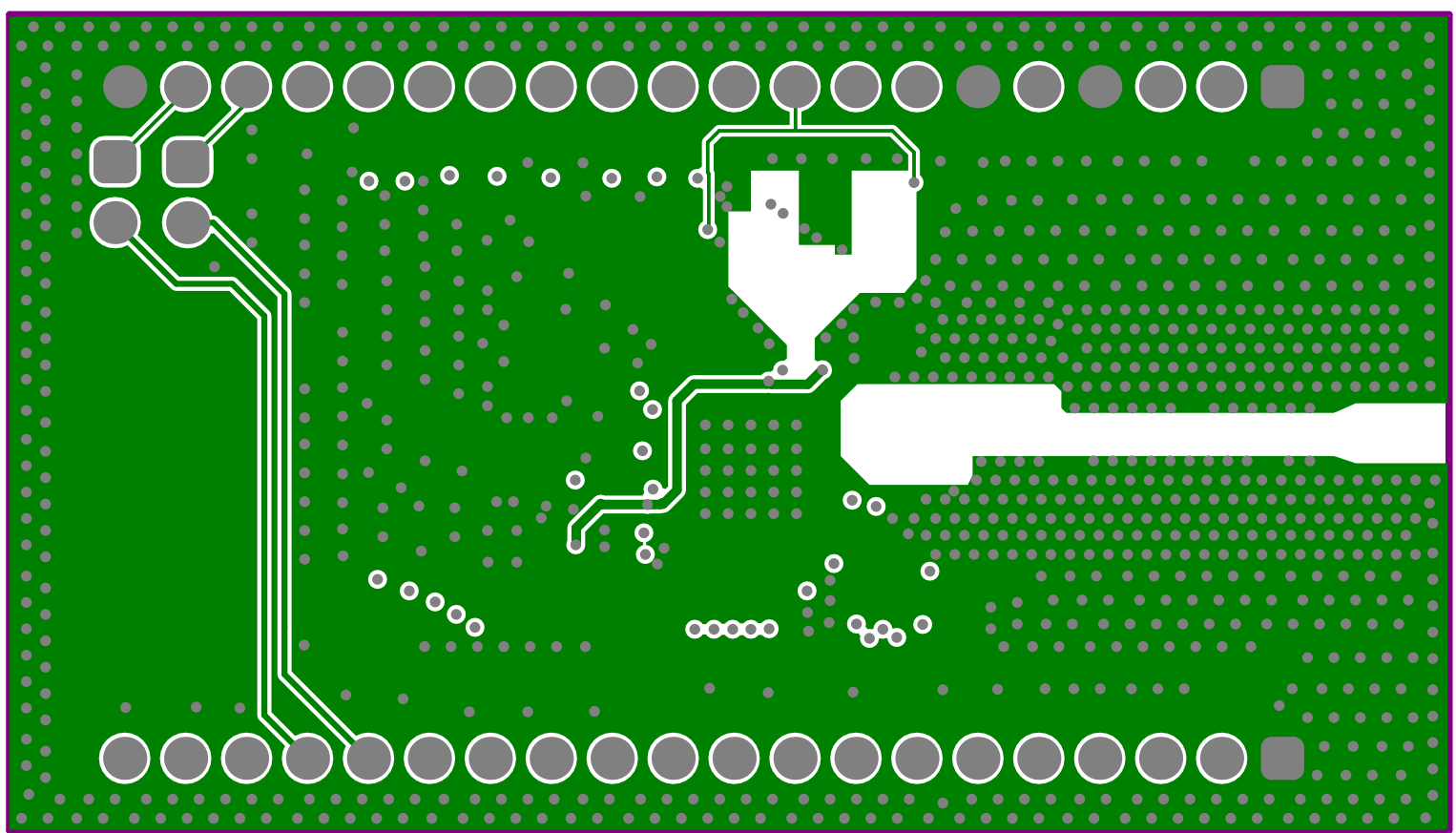



Project: STM32WL_QFN48_LP_DirectTie_RefBoard		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1789_LP	
Date: 01-04-2022	Rev: A	

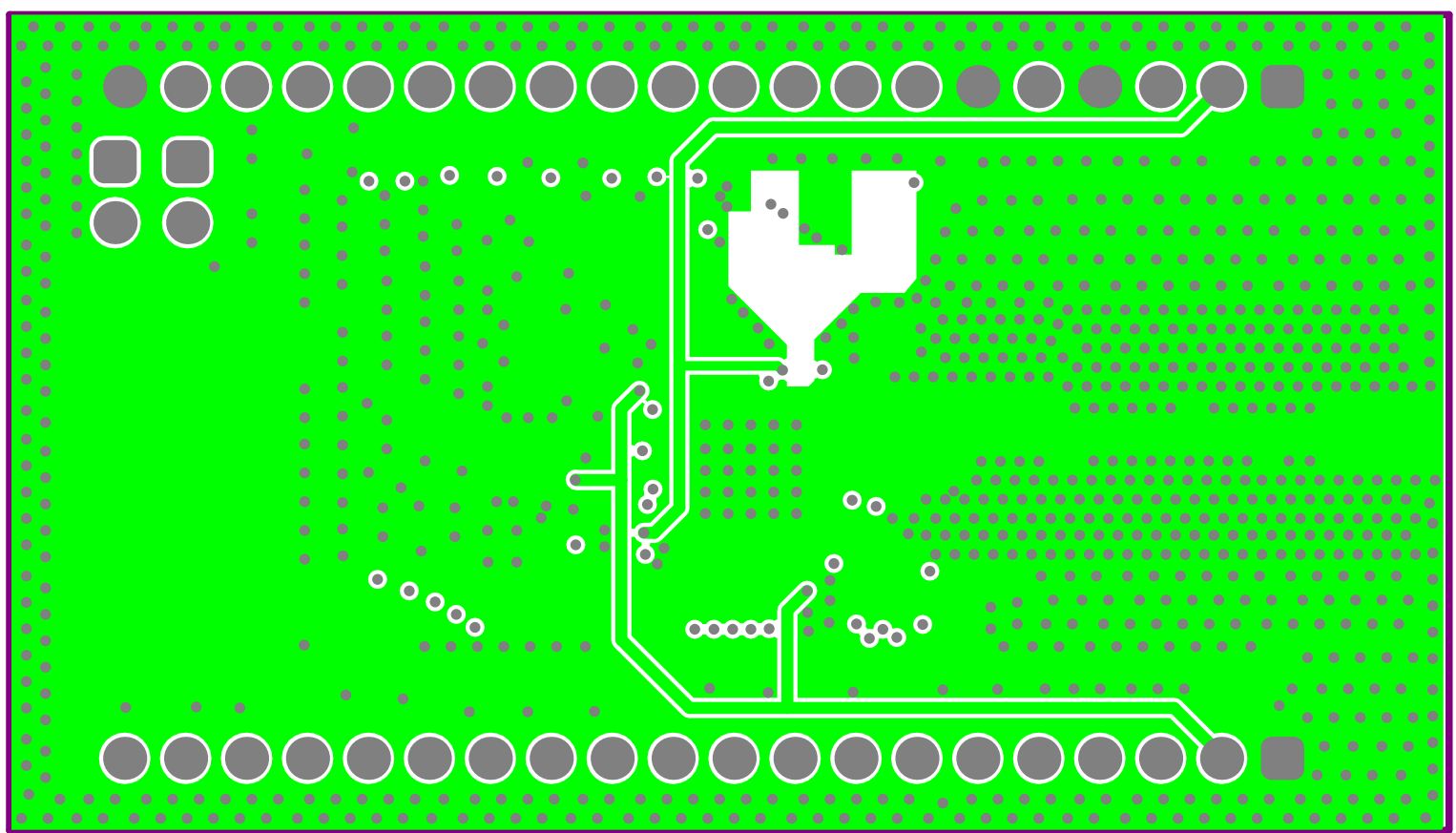
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.79mil	3.7	
1	Top Layer	Copper	1.38mil		
	Dielectric 1	1x106 + 1x2116	6.30mil	3.7	
2	Mid-Layer 1	Copper	1.38mil		
	Dielectric2	FR-4	24.02mil	5	
3	Mid-Layer 2	Copper	1.38mil		
	Dielectric3	1x106 + 1x2116	6.30mil	3.7	
4	Bottom Layer	Copper	1.38mil		
	Bottom Solder	Solder Resist	0.79mil	3.7	
	Bottom Overlay				




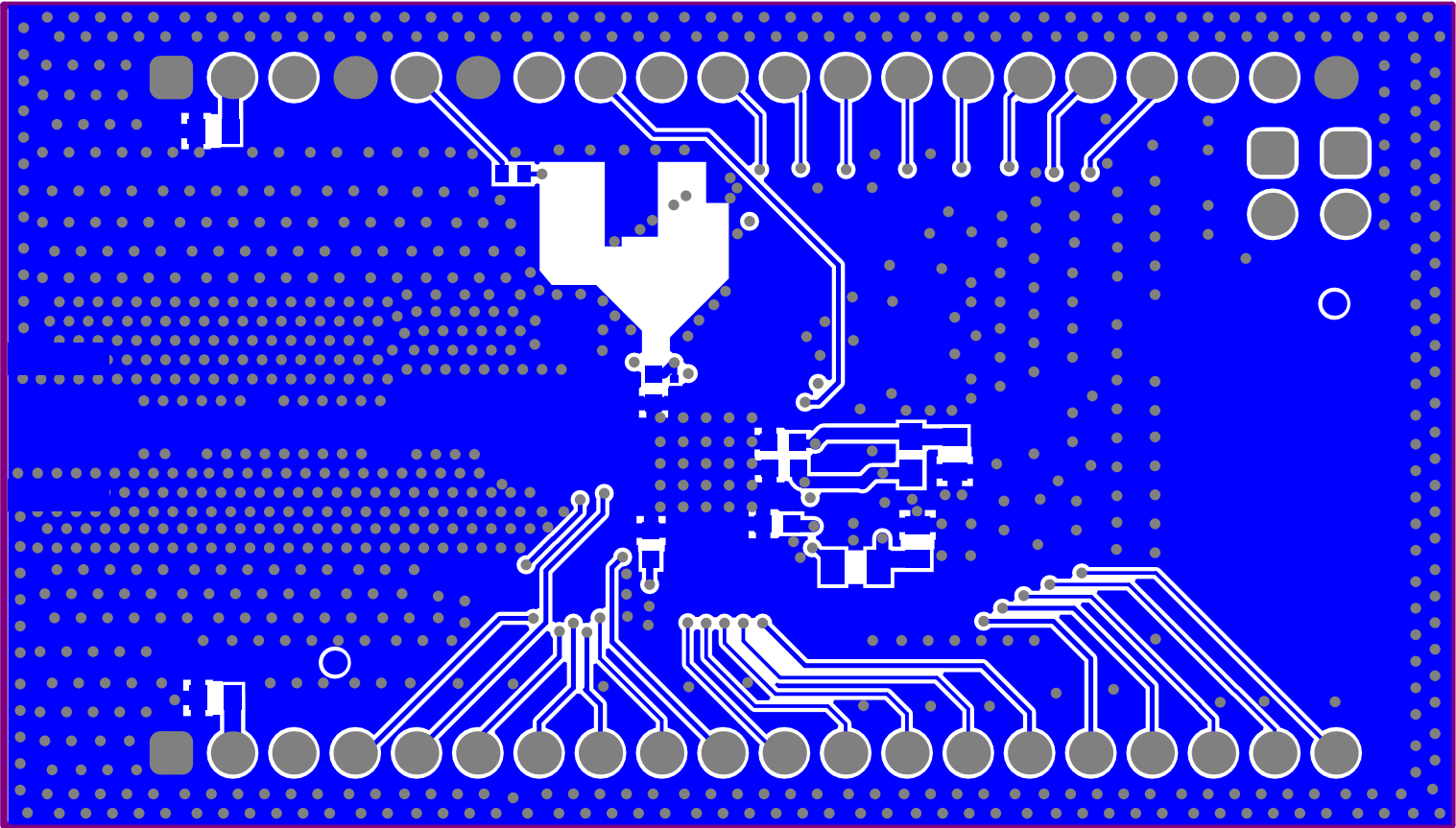
Project: STM32WL_QFN48_LP_DirectTie_RefBoard		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1789_LP	
Date: 01-04-2022	Rev: A	



Project: STM32WL_QFN48_LP_DirectTie_RefBoard		
Layer: Mid-Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB1789_LP	
Date: 01-04-2022	Rev: A	

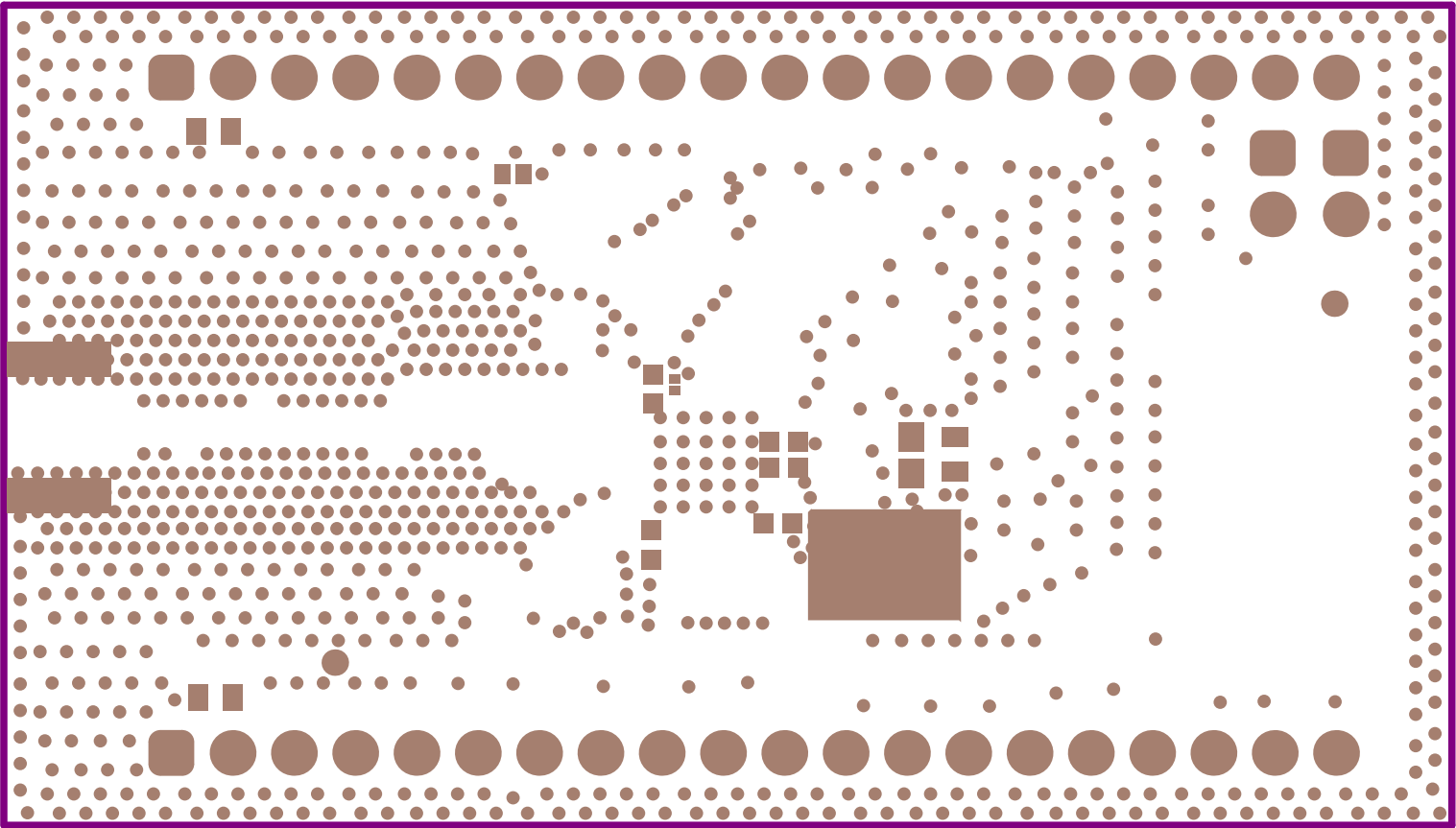


Project: STM32WL_QFN48_LP_DirectTie_RefBoard		
Layer: Mid-Layer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB1789_LP	
Date: 01-04-2022	Rev: A	



Project: STM32WL_QFN48_LP_DirectTie_RefBoard	
Layer: Bottom Layer	Gerber: .GBL
Variant: [No Variations]	Ref: MB1789_LP
Date: 01-04-2022	Rev: A





Project: STM32WL_QFN48_LP_DirectTie_RefBoard

Layer: Bottom Solder

Gerber:.GBS

Variant: [No Variations]

Ref: MB1789_LP

Date: 01-04-2022

Rev: A



Project: STM32WL_QFN48_LP_DirectTie_RefBoard

Layer: Bottom Overlay

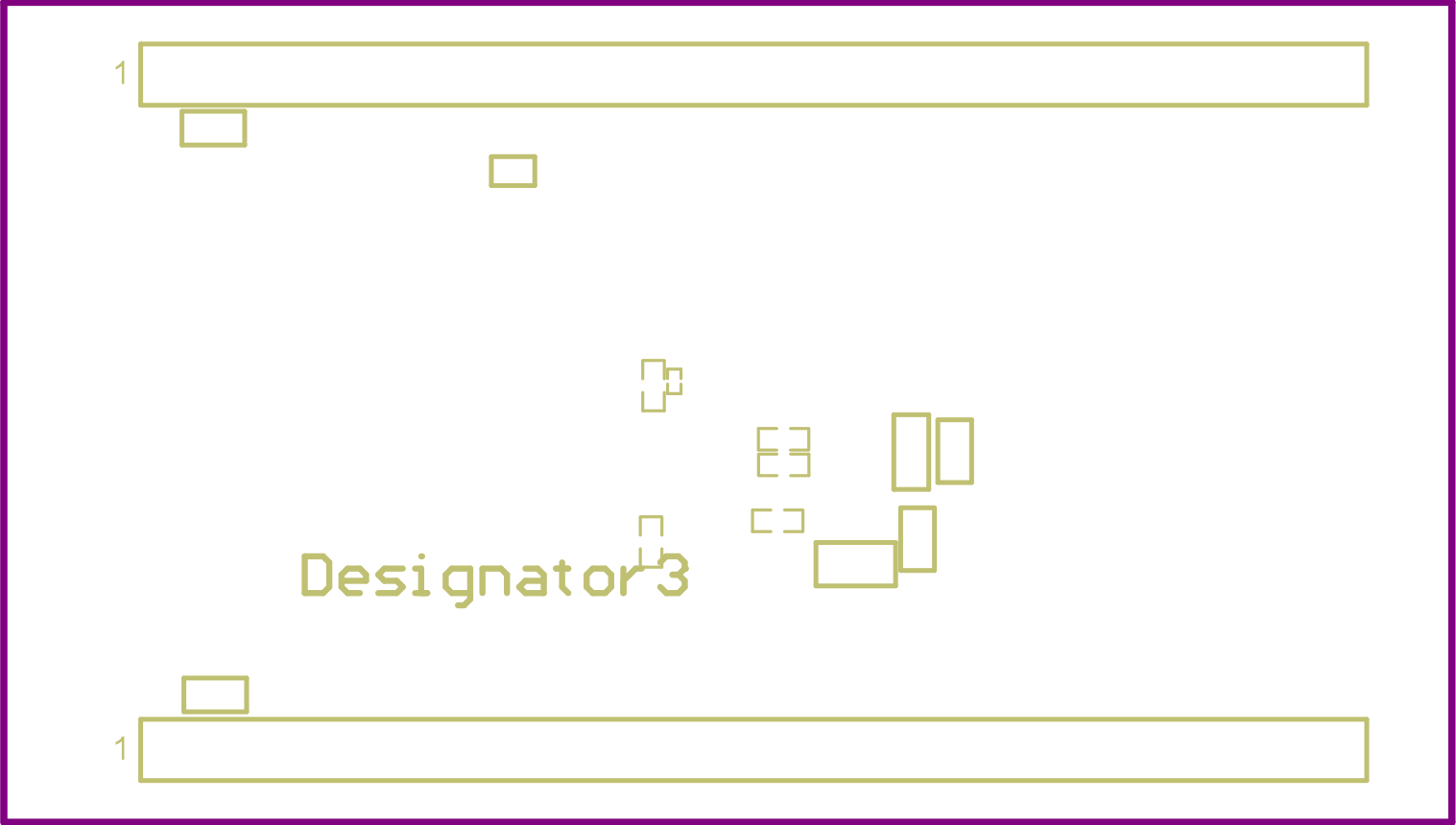
Gerber: GBO



Variant: [No Variations]

Ref: MB1789_LP

Date: 01-04-2022

Rev: A



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description
	44	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)	
	993	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)	
	1037 Total								

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differential)	TOL.
TOP	27.6	7.28	50 ohm	NA	+/- 10%

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☒TG-170

☐TG-150

☐TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☒GREEN

☐BLUE

☐RED

☐BLACK

D. SILKSCREEN COLOR :

☒WHITE

☐YELLOW

☐BLACK

E. SURFACE FINISH :

☒ENIG

☐IMMERSION SILVER

☐IMMERSION TIN

☐HASL

☐HASL (PB-FREE)

☐GOLDEN FINGER

☐IMPEDANCE CONTROL :

☐NO

☒YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

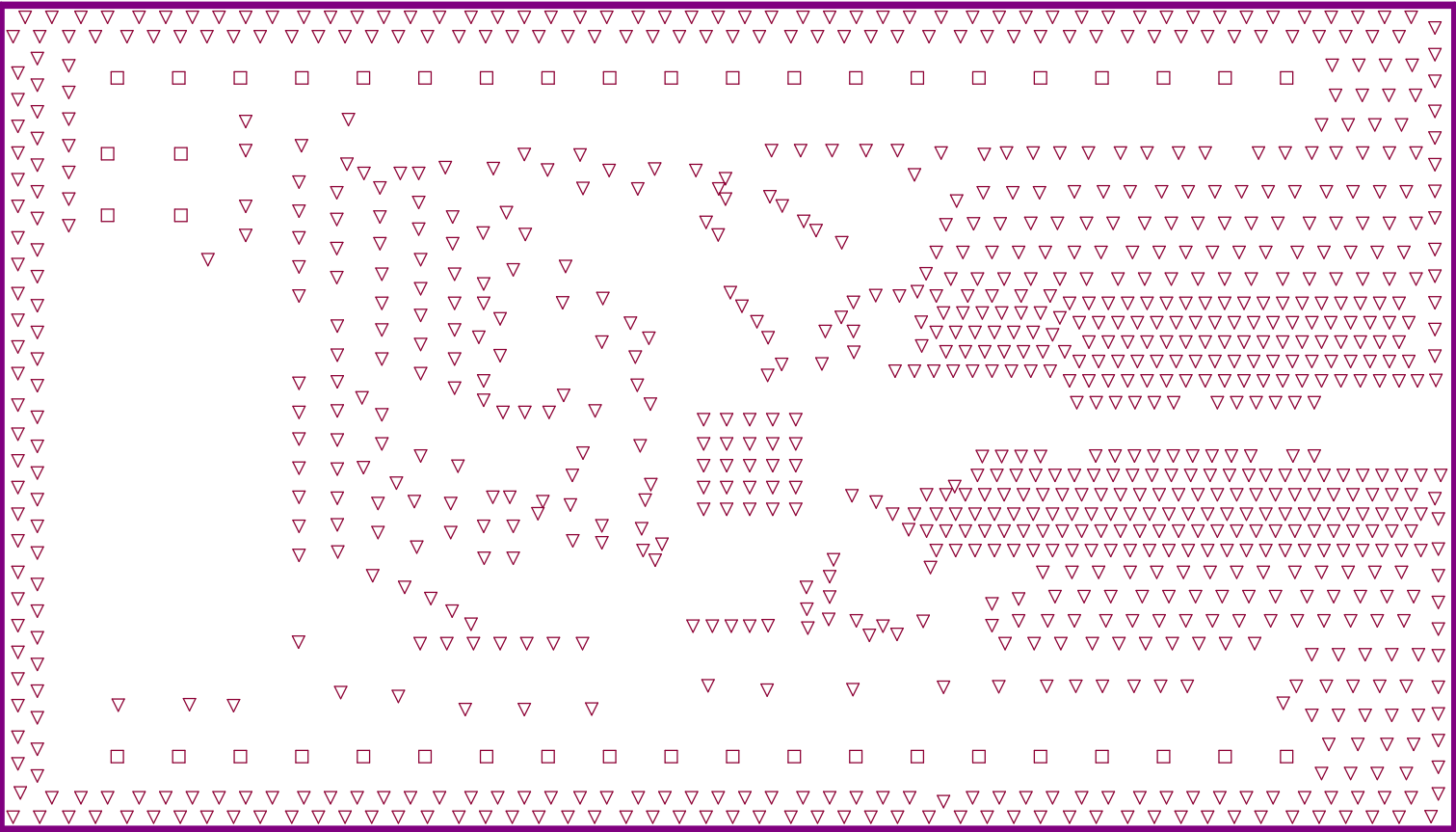
PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL :


☒SOLDERMASK

☐NON-CONDUCTIVE EPOXY.

☐STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32WL_QFN48_LP_DirectTie_RefBoard		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1789_LP	
Date: 01-04-2022	Rev: A	